Ferrite Chip Bead for GHz Range Noise Suppression (Lead Free)

GHB0603HF-Series

| ECN HISTORY LIST | | | | | | | | |
|------------------|----------|---|----------|---------|-------|--|--|--|
| REV | DATE | DESCRIPTION | APPROVED | CHECKED | DRAWN | | | |
| 1.0 | 13/10/29 | 初版發行 | 楊祥忠 | 羅培君 | 張嘉玲 | | | |
| 2.0 | 14/01/24 | 變更電鍍錫層厚度 3.0um min.=>3.5um min. | 楊祥忠 | 羅培君 | 張嘉玲 | | | |
| 3.0 | 14/08/01 | 變更 Reflow 圖示 | 楊祥忠 | 羅培君 | 張嘉玲 | | | |
| 4.0 | 16/01/26 | 增訂可靠度 Thermal shock: (Bead) Step3:125±2℃ 30±5min | 楊祥忠 | 詹偉特 | 張嘉玲 | | | |
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TAI-TECH **TBM01-160601005** P2.

Ferrite Chip Bead for GHz Range Noise Suppression (Lead Free)

GHB0603HF-Series

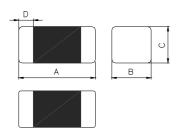
1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3.S.M.T. type.
- 4. Suitable for reflow soldering.
- 5. The GHB1005 series is intended for standard signal lines as this series provides significant impedance across a broad frequency range.
- 6. The magnetic shielded structure minimizes crosstalk.
- 7.100% Lead(Pb) & Halogen-Free and RoHS compliant.





2.Dimensions



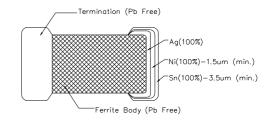
| Chip Size | | | | | |
|-----------|-----------|--|--|--|--|
| Α | 0.60±0.03 | | | | |
| В | 0.30±0.03 | | | | |
| С | 0.30±0.03 | | | | |
| D | 0.15±0.05 | | | | |

Unit: mm

3.Part Numbering



- **B**: Dimension
- LxW C: Material Lead Free Material 102=1000 Ω
- D: Impedance
- E: Packaging T=Taping and Reel, B=Bulk(Bags)
- F: Rated Current



4. Specification

| Tai-Tech Impedance (Ω) | | Test Frequency (Hz) | DC Resistance (Ω) max. | Rated Current (mA) max. | |
|-------------------------------|----------|------------------------|-------------------------------|----------------------------|--|
| GHB0603HF-601T01 | 600±25% | 60mV/100M | 1.5 | 160 | |
| GHB0603HF-102T01 | 1000±25% | 60mV/100M | 2.5 | 130 | |
| GHB0603HF-152T01 | 1500±25% | 60mV/100M | 3.2 | 115 | |

- Rated current: based on temperature rise test
- In compliance with EIA 595

TAI-TECH TBM01-160601005 P3.

5. Reliability and Test Condition

| Item | | | | Perfor | mance | | | | | Tes | t Con | dition | |
|---------------------------------------|---|--|------------------------------------|------------------------|-------------|-----------------------|--|---|---|------------------------------|--------------------------------------|------------------------------------|--|
| Series No. | FCB FCM | НСВ | GHB | FCA | FCI | FHI | FCH | HCI | | | | | |
| Operating Temperature | (Including | -40~+125 self-temp | | rise) | (Inc | -40~- luding self- | +105°ℂ temperatui | e rise) | | | | | |
| Transportation Storage Temperature | | -40~+125 (on board | - | | | | +105℃ board) | | For long storage conditions, please see the Application Notice | | | | |
| Impedance (Z) | | | | | | | | | Agilent429 | 91 | | | |
| Inductance (Ls) | | | | | | | | | Agilent E4 | | | | |
| Q Factor | Refer to stan | dard elec | trical ch | aracteris | tics list | | | | Agilent428 Agilent161 | | | | |
| DC Resistance | recici to stair | idala cico | uroar orie | aracterio | tios iist | | | | Agilent 433 | | | | |
| Rated Current | | | | | | | | | DC Power Over Rates some risk | d Curre | | ements, the | ere will be |
| Temperature Rise Test | | Rated Current < 1A ΔT 20 $^{\circ}$ Max Rated Current \geq 1A ΔT 40 $^{\circ}$ Max | | | | | | | Applied Tempera thermore | ature m | | current. by digital s | urface |
| | | | | | | | | | Number of | f heat c | ycles: 1 | | |
| Resistance to Soldering | Appearance Impedance : | | | tial value | e | | | | Temperatu (°C) | | Time (s) | Temperati ramp/imm and emers | ersion |
| Heat | Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | | | | | 260 ±5 (solder ten | mp) | 10 ±1 | 25mm/s | ±6 mm/s | | | |
| | Table and and some more openinguity value | | | | | | Depth: completely cover the termination | | | ion | | | |
| Solderability | | More than 95% of the terminal electrode should be covered with solder. | | | | | | Preheat: 150℃, 60sec. Solder: Sn96.5%-Ag3%-Cu0.5% Solder temperature: 245±5℃ Flux for lead free: Rosin. 9.5% Depth: completely cover the termination. Dip time: 4±1sec. | | | | | |
| Terminal strength | Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value | | | | | _ | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Component mounted on a PCB apply a force (>0805:1kg <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested. | | | | | | |
| Bending | Appearance: No damage. Impedance: within±10% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value | | | | | on value | Shall be mounted on a FR4 substrate of the following dimensions:>=0805:40x100x1.2mm | | | | | | |
| Vibration Test | Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | | | | | on value | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycleseach of 3 orientations) | | | | | | |
| | | | | | | | | | Test cond | dition: | | | |
| Shock | Appearance Impedance : Inductance : Q : Shall not RDC : within | within±10 within±10 exceed the | 0% of ini 0% of ini ne speci | tial value fication | e value. | exceed the | specification | on value | Туре | Peak Value (g's) 50 | Normal duration (D) (ms) 11 | Wave form Half-sine | Velocity change (Vi)ft/sec 11.3 |

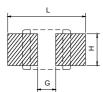
TAI-TECH TBM01-160601005 P4.

| Item | Performance | Test Condition | | |
|-----------------------|--|--|--|--|
| Life test | Appearance: no damage. Impedance: within±15%of initial value. | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 125±2°C (Bead), | | |
| Load Humidity | Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | IOI 24±2 IIIS. Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24+2 hrs. | | |
| Thermal shock | Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: 40±2°C 30±5 min. Step2: 25±2°C ≤0.5min Step3: +125±2°C 30±5min. (Bead) Step3: +105±2°C 30±5min. (Inductor) Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs. | | |
| Insulation Resistance | IR>1GΩ | Chip Inductor Only Test Voltage:100±10%V for 30Sec. | | |

6. Soldering and Mounting

6-1. Recommended PC Board Pattern

| Chip Size | | | | | | Land Patterns For Reflow Soldering | | |
|-----------|------|----------|-----------|-----------|-----------|---------------------------------------|-------|-------|
| Series | Туре | A(mm) | B(mm) | C(mm) | D(mm) | L(mm) | G(mm) | H(mm) |
| GHB | 0603 | 0.6±0.03 | 0.30±0.03 | 0.30±0.03 | 0.15±0.05 | 0.80 | 0.30 | 0.30 |



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

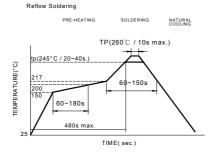
6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

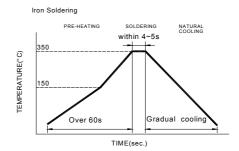
6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

- Preheat circuit and products to 150°C
 350°C tip temperature (max)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- · Limit soldering time to 4~5sec.



Reflow times: 3 times max Fig.1

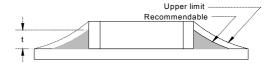


Iron Soldering times: 1 times max Fig.2

6-2.3 Solder Volume:

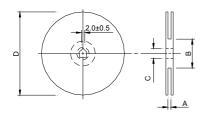
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

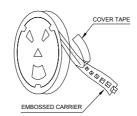
Minimum fillet height = soldering thickness + 25% product height



7. Packaging Information

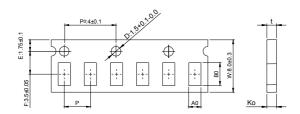
7-1. Reel Dimension





| Туре | A(mm) | B(mm) | C(mm) | D(mm) |
|--------|--------|--------|--------|-------|
| 7"x8mm | 10±1.5 | 50 min | 13±0.2 | 178±2 |

7-2. Tape Dimension / 8mm



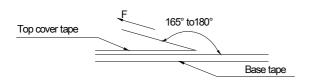
| Size | Bo(mm) | Ao(mm) | Ko(mm) | P(mm) | t(mm) |
|--------|-----------|-----------|---------|----------|---------|
| 060303 | 0.70±0.06 | 0.40±0.06 | 0.45max | 2.0±0.05 | 0.50max |

TAI-TECH TBM01-160601005 P6.

7-3. Packaging Quantity

| Chip Size | 060303 |
|-------------|--------|
| Chip / Reel | 15000 |
| Inner box | 75000 |
| Middle box | 375000 |
| Carton | 750000 |

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

| Room Temp. | om Temp. Room Humidity | | Tearing Speed | |
|------------|------------------------|----------|---------------|--|
| (℃) | (%) | (hPa) | mm/min | |
| 5~35 | 45~85 | 860~1060 | 300 | |

Application Notice

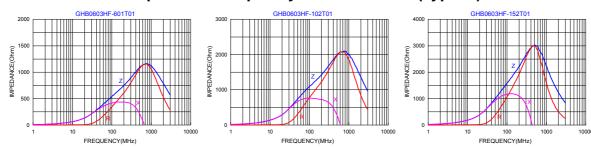
· Storage Conditions

To maintain the solder ability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40 $^{\circ}\mathrm{C}\,$ and 60% RH.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

TAI-TECH TBM01-160601005 P7.

Impedance Frequency Characteristics(Typical)





with SGS www.tw.sgscom

測試報告

Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 1 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(耀鑚科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

(廣邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN,

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (桃園市中堰區中堰工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI DISTRICT, TAOYUAN CITY 320, TAIWAN)

(江蘇省宿遷市泗洪縣經濟開發區金沙南路-高新技術產業園 / HIGH-TECH INDUSTRIAL DISTRICT, JINSHAJIANG ROAD, SIHONG COUNTY ECONOMIC, SUQIAN

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

樣品型號(Style/Item No.)

FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

收件日期(Sample Receiving Date)

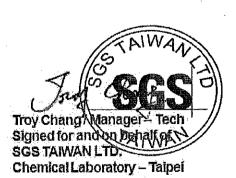
2015/12/14

測試期間(Testing Period)

2015/12/14 TO 2015/12/21

測試結果(Test Results)

請見下一頁 (Please refer to next pages).



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 2 of 16

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測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限值 | 結果 (Result) |
|----------------------------------|--------------|--|-------------|-------------|
| (1001 11000) | (5111.67 | (20 001) | (MDL) | No. 1 |
| 鎬 / Cadmium (Cd) | mg/kg | 参考IEC 62321-5: 2013方法,以感應 耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-5: 2013 and performed by ICP-AES. | 2 | n. d. |
| 鉛 / Lead (Pb) | mg/kg | 參考IEC 62321-5: 2013方法,以感應 耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-5: 2013 and performed by ICP-AES. | 2 | 25. 7 |
| 汞 / Mercury (Hg) | mg/kg | 参考IEC 62321-4: 2013方法,以感應 耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-4: 2013 and performed by ICP-AES. | 2 | n. d. |
| 六價鉻 / Hexavalent Chromium Cr(VI) | mg/kg | 参考IEC 62321: 2008方法,以UV-VIS 檢測. / With reference to IEC 62321: 2008 and performed by UV- VIS. | 2 | n. d. |
| 銻 / Antimony (Sb) | mg/kg | 参考US EPA 3052方法,以感應耦合電 漿原子發射光譜儀檢測. / With reference to US EPA Method 3052. Analysis was performed by ICP-AES. | 2 | n. d. |
| 鈹 / Beryllium (Be) | mg/kg | 參考US EPA 3052方法,以感應耦合電 漿原子發射光譜儀檢測. / With reference to US EPA Method 3052. Analysis was performed by ICP-AES. | 2 | n. d. |

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| 测試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限値 (MDL) | 結果 (Result) |
|--|--------------|--|----------------------|----------------|
| 全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide) | mg/kg | 参考US EPA 3550C: 2007方法, 以液相 層析/質譜儀檢測. / With reference to US EPA 3550C: 2007. Analysis was performed by LC/MS. | 10 | No. 1 n. d. |
| 全氟辛酸 / PFOA (CAS No.: 335-67-1) | mg/kg | 參考US EPA 3550C: 2007方法, 以液相 層析/質譜儀檢測. / With reference to US EPA 3550C: 2007. Analysis was performed by LC/MS. | 10 | n. d. |
| 聚氯乙烯 / PVC | ** | 以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test. | _ | Negative |
| 鄭某二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7) | mg/kg | 參考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |
| 鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2) | mg/kg | 參考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 4 of 16

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| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限値 (MDL) | 結果 (Result) |
|--|--------------|--|----------------------|----------------|
| 鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7) | mg/kg | 参考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | No. 1 n. d. |
| 鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No.: 84-69-5) | mg/kg | 李考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |
| 鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1) | mg/kg | 參考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之,/ With reference to IEC 62321-8 (111/321/CD), Analysis was performed by GC/MS. | 50 | n. d. |
| 鄰苯二甲酸二異壬酯 / DINP (Di-isononyl phthalate) (CAS No.: 28553-12-0; 68515-48-0) | mg/kg | 參考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |
| 鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0) | mg/kg | 參考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 5 of 16

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| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法侦测 極限値 (MDL) | 結果 (Result) |
|---|--------------|--|----------------------|-------------|
| | | | | No. 1 |
| 鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3) | mg/kg | 参考IEC 62321-8 (111/321/CD),以氣相層析儀/質譜儀檢測之. / With reference to IEC 62321-8 (111/321/CD). Analysis was performed by GC/MS. | 50 | n. d. |
| 六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8)) | mg/kg | 参考IEC 62321: 2008方法,以氣相層析/質譜儀檢測. / With reference to IEC 62321: 2008 method. Analysis was performed by GC/MS. | 5 | n. d. |
| 鹵素 / Halogen | | | | |
| 鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8) | mg/kg | 参考BS EN 14582:2007,以離子層析儀 分析. / With reference to BS EN 14582:2007. Analysis was performed by IC. | 50 | n. d. |
| 鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1) | mg/kg | | 50 | n. d. |
| 鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2) | mg/kg | | 50 | n. d. |
| 鹵素(碘)/ Halogen-Iodine (I) (CAS No.: 14362-44-8) | mg/kg | | 50 | n. d. |

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 6 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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| 測試項目 (Took Itoma) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限值 | 結果 (Result) |
|----------------------------------|--------------|---|-------------|-------------|
| (Test Items) | (0017) | (method) | (MDL) | No. 1 |
| 多溴聯苯總和 / Sum of PBBs | mg/kg | | _ | n, d, |
| 一溴聯苯 / Monobromobiphenyl | mg/kg | | 5 | n. d. |
| 二溴聯苯 / Dibromobiphenyl | mg/kg |] | 5 | n. d. |
| 三溴聯苯 / Tribromobiphenyl | mg/kg | | 5 | n. d. |
| 四溴聯苯 / Tetrabromobiphenyl | mg/kg | | 5 | n. d. |
| 五溴聯苯 / Pentabromobiphenyl | mg/kg | 1 | 5 | n. d. |
| 六溴聯苯 / Hexabromobiphenyl | mg/kg |] | 5 | n. d. |
| 七溴聯苯 / Heptabromobiphenyl | mg/kg |] | 5 | n. d. |
| 八溴聯苯 / Octabromobiphenyl | mg/kg | · [| 5 | n. d. |
| 九溴聯苯 / Nonabromobiphenyl | mg/kg | | 5 | n. d. |
| 十溴聯苯 / Decabromobiphenyl | mg/kg | 層析/質譜儀檢測. / With reference to IEC 62321-6: 2015 and performed by GC/MS. | 5 | n. d. |
| 多溴聯苯醚總和 / Sum of PBDEs | mg/kg | | - | n. d. |
| 一溴聯苯醚 / Monobromodiphenyl ether | mg/kg | | 5 | n. d. |
| 二溴聯苯醚 / Dibromodiphenyl ether | mg/kg | Ī | 5 | n. d. |
| 三溴聯苯醚 / Tribromodiphenyl ether | mg/kg |] · [| 5 | n. d. |
| 四溴聯苯醚 / Tetrabromodiphenyl ether | mg/kg | 1 | 5 | n. d. |
| 五溴聯苯醚 / Pentabromodiphenyl ether | mg/kg | · | 5 | n. d. |
| 六溴聯苯醚 / Hexabromodiphenyl ether | mg/kg | | 5 | n. d. |
| 七溴聯苯醚 / Heptabromodiphenyl ether | mg/kg | | 5 | n. d. |
| 八溴聯苯醚 / Octabromodiphenyl ether | mg/kg | | 5 | n. d. |
| 九溴聯苯醚 / Nonabromodiphenyl ether | mg/kg | | 5 | n. d. |
| 十溴聯苯醚 / Decabromodiphenyl ether | mg/kg |] [| 5 | n. d. |



Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 7 of 16

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備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. **= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
- 7. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS參考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 757/2010

PFOS濃度在物質或製備中不得超過0.001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或塗 層材料中不得超過1µg/m²。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above $1\mu g/m^2$.)

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 8 of 16

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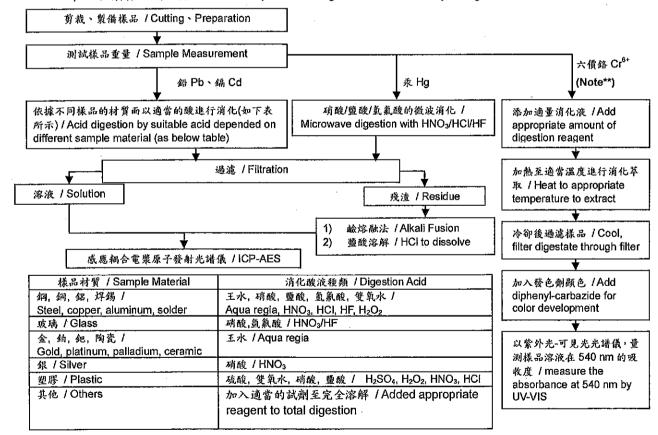
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重金屬流程圖 / Analytical flow chart of Heavy Metal (IEC 62321)

- 1) 根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外) / These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr6+ test method excluded)
- 測試人員:楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 測試負責人: 張啟與 / Name of the person in charge of measurement: Troy Chang



Note**: (1) 針對非金屬材料加入鹼性消化液,加熱至 90~95℃萃取. / For non-metallic material, add alkaline digestion reagent and heat to 90~95°C.

(2) 針對金屬材料加入純水,加熱至沸騰萃取. / For metallic material, add pure water and heat to boiling.

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 9 of 16

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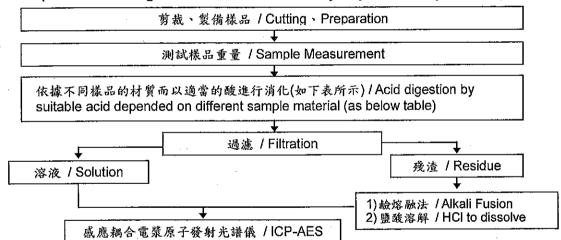
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- 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.
- 測試人員:楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 測試負責人:張啟興 / Name of the person in charge of measurement: Troy Chang

元素以 ICP-AES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-AES)



| 鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder | 王水,硝酸,鹽酸,氫氟酸,雙氧水 / Aqua regia, HNO ₃ , HCI, HF, H ₂ O ₂ |
|---|--|
| 玻璃 / Glass | 硝酸,氫氟酸 / HNO ₃ /HF |
| 金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic | 王水 / Aqua regia |
| 銀 / Silver | 硝酸 / HNO ₃ |
| 塑膠 / Plastic | 硫酸,雙氧水,硝酸,鹽酸 / H ₂ SO ₄ , H ₂ O ₂ , HNO ₃ , HCl |
| 其他 / Others | 加入適當的試劑至完全溶解 / Added appropriate reagent to total digestion |

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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 10 of 16

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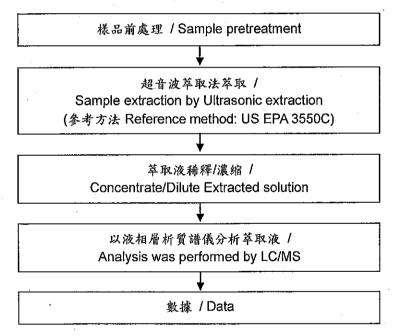
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全氟辛酸/全氟辛烷磺酸分析流程圖 / PFOA/PFOS analytical flow chart

- 測試人員: 翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啟興 / Name of the person in charge of measurement. Troy Chang



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 11 of 16

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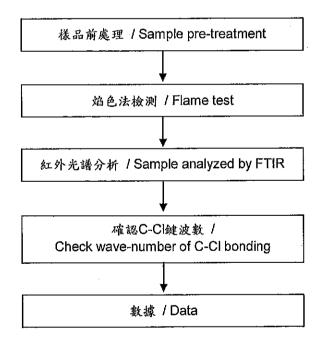
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聚氮乙烯物質判定分析流程圖 /

Analysis flow chart for determination of PVC in material

- 測試人員: 林建宇 / Name of the person who made measurement. Roy Lin
- 測試負責人: 張啟興 / Name of the person in charge of measurement: Troy Chang



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 12 of 16

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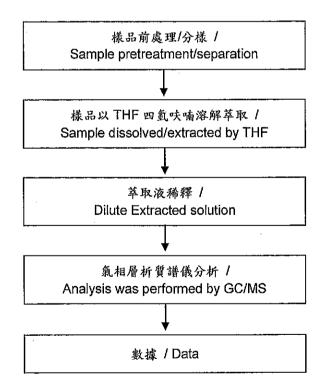
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可塑劑分析流程圖 / Analytical flow chart of phthalate content

- 測試入員:徐毓明 / Name of the person who made measurement: Andy Shu
- 測試負責人:張啟興 / Name of the person in charge of measurement: Trov Chang

【測試方法/Test method: IEC 62321-8】



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 13 of 16

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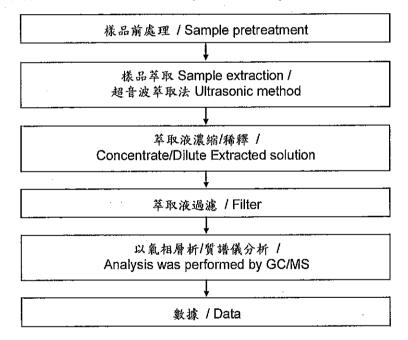
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六溴環十二烷分析流程圖 / HBCDD analytical flow chart

- 测試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啟興 / Name of the person in charge of measurement: Troy Chang



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 14 of 16

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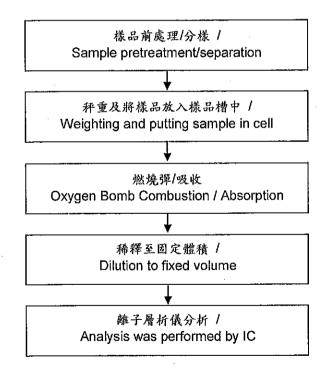
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鹵素分析流程圖 / Analytical flow chart of halogen content

- 測試人員: 陳恩臻 / Name of the person who made measurement: Rita Chen
- 测試負責人:張啟興 / Name of the person in charge of measurement: Troy Chang



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 15 of 16

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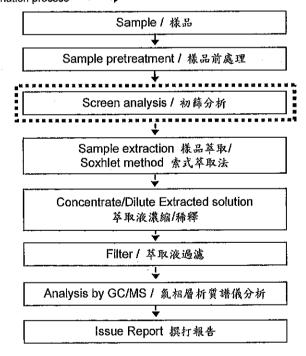
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多溴聯苯/多溴聯苯醚分析流程圖 / PBB/PBDE analytical FLOW CHART

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啟興 / Name of the person in charge of measurement: Troy Chang

初次測試程序 / First testing process --選擇性篩檢程序 / Optional screen process • • • • • • •

確認程序 / Confirmation process - · - · ▶



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Test Report

號碼(No.): CE/2015/C2559

日期(Date): 2015/12/21

頁數(Page): 16 of 16

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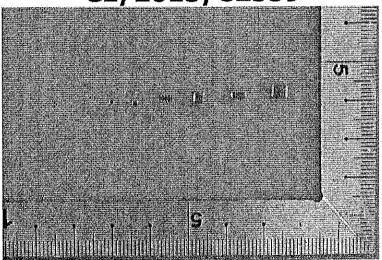
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* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. * (The tested sample / part is marked by an arrow if it's shown on the photo.)

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